

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: H. KOMATSU, et al.  
Serial No.: 10/594,548  
Filed: SEPTEMBER 27, 2006  
For: HEAT-RESISTANT PHOTSENSITIVE RESIN  
COMPOSITION, METHOD FOR FORMING PATTERN USING  
THE COMPOSITION, AND ELECTRONIC PART  
Group AU: 1795  
Examiner: John S. Y. Chu  
Confirm. No.: 3540

**SUBMISSION UNDER 37 CFR 1.114  
(AMENDMENT)**

**Mail Stop: RCE - FEE**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

January 25, 2010

Sir:

In response to the Office Action dated October 23, 2009, and concurrently with the filing of a Request for Continued Examination (RCE) Transmittal, please amend the above-identified application as listed in the following, and as set forth on the following pages:

AMENDMENTS TO THE CLAIMS; and

REMARKS are included following the amendments.

